

Title (en)

METHOD AND SYSTEM FOR PRODUCING PRINTED CIRCUIT BOARDS WITH PERFORATED MOLDED PARTS

Title (de)

VERFAHREN UND SYSTEM ZUR HERSTELLUNG VON LEITERPLATTEN MIT GELOCHTEN FORMTEILEN

Title (fr)

PROCÉDÉ ET SYSTÈME POUR FABRIQUER DES CARTES DE CIRCUITS IMPRIMÉS AVEC DES PIÈCES DE FORME PERFORÉES

Publication

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Application

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Abstract (en)

[origin: WO2022214425A1] The invention relates to a method and a system for producing printed circuit boards (1) with perforated molded parts (2). The aim of the invention is to allow a high degree of positioning accuracy of the elements to be pressed of a printed circuit board (1) during the pressing process. This is achieved in that the perforated molded parts (2) are arranged and fixed relative to one another in a specified configuration in order to form a semi-finished product (9) with a perforated mask (L), wherein the semi-finished product (9) is then positioned in a press (4) using the perforated mask (L) and is pressed together with at least one other element (8, 10, 12) in order to form a printed circuit board substrate for producing a printed circuit board (1). The invention also relates to a system for producing printed circuit boards (1) in order to prepare corresponding semi-finished products (9) and processing same in order to form a printed circuit board substrate for producing a printed circuit board (1).

IPC 8 full level

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